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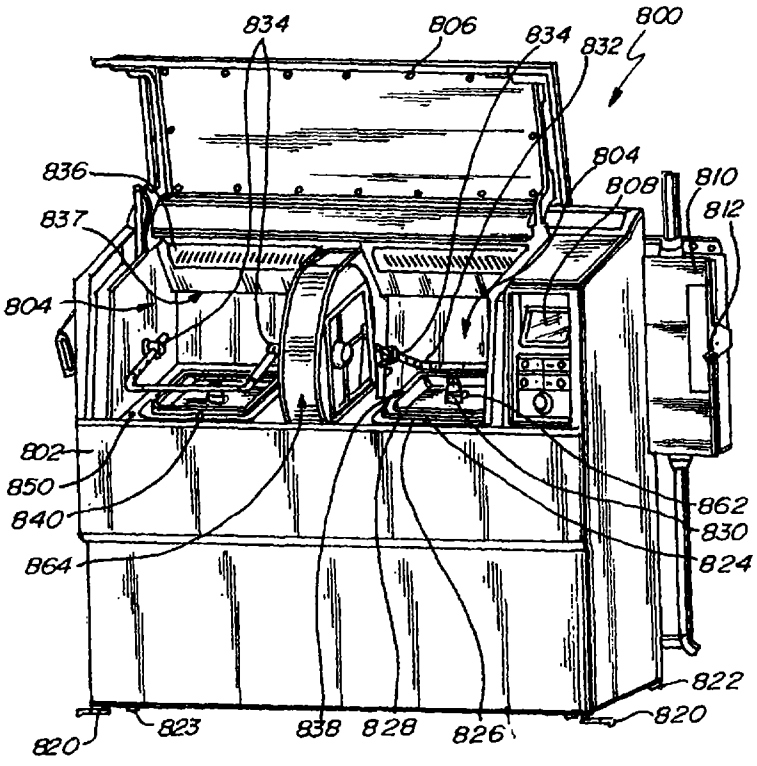
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(54) Title: WAFER CONTAINER WASHING APPARATUS



(57) Abstract: The present invention is directed to a semi-conductor handling equipment cleaning method and apparatus configured for use with wafer carriers (c). The cleaning apparatus (10) comprises a base portion (24) having a first aperture (22) and a second aperture (16). The base (24) is configured to support the wafer carrier (c) in sealing contact about the first aperture (22). A first fluidic circuit (50) is provided for introducing a first cleaning fluid to the inner surface of carrier (c). A second fluidic circuit (30, 38, 34) is provided for introducing a second cleaning fluid to the outer surface of the carrier (c). The carrier (c) forms a barrier with a base (24) so that the cleaning media is isolated so as to substantially prevent the second fluid used to clean the exterior from communicating with the first fluid used to clean the interior of the carrier (c). A door cleaning assembly (864) may be provided as part of the cleaning apparatus (10). The door cleaning assembly (864) comprises a rotational housing (866), a shaft (868) disposed in the housing (864) and a door receiving assembly (872) rotatably disposed on the shaft (868) and within the housing (866). The door receiving assembly (872) is configured to securably receive the door (P) and to form a fluid tight seal between the door (P) and the door receiving assembly (872). The door receiving assembly (872), with a carrier door (P) disposed therein is configured to minimize introduction of the second cleaning fluid into the first cleaning fluid.

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— *with amended claims*

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